



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
**MEARS**

Serial No. NOT YET ASSIGNED

Filing Date: HEREWITH

For: METHOD FOR MAKING  
SEMICONDUCTOR DEVICE  
INCLUDING BAND-ENGINEERED  
SUPERLATTICE

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DATE OF DEPOSIT: November 19, 2003

NAME: Justin Goree

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CITATION UNDER 37 CFR §1.97

Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Attached is a form PTO-1449 listing several  
references for consideration in the examination of the above-  
identified application. A copy of each reference may be found  
in parent application, Serial No. 10/647,061 filed August 22,  
2003. It is requested that these references be considered by  
the Examiner and officially made of record in accordance with  
the provisions of 37 CFR §1.97 and Section 609 of the MPEP.

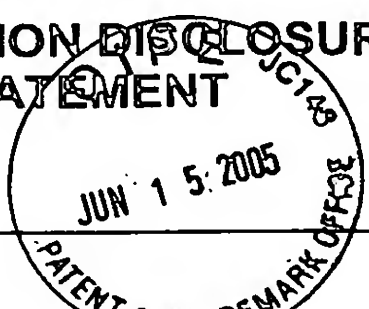
Respectfully submitted,

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<b>INFORMATION DISCLOSURE STATEMENT</b> 	Atty Docket:	62603_CON2
	Serial No.:	NOT YET ASSIGNED
	Applicant:	MEARS
	Filing Date:	HEREWITH
	Group:	

U.S. PATENT DOCUMENTS							
Examiner Initials		Document Number	Date	Name	Class	Sub Class	Filing Date
	AA	4,594,603	06/10/86	Holonyak, Jr.	357	16	01/24/85
	AB	4,937,204	06/26/90	Ishibashi et al.	437	110	01/4/89
	AC	4,969,031	11/06/90	Kobayashi et al.	357	63	02/3/83
	AD	5,05,887	10/08/91	Yamazaki	357	4	01/18/90
	AE	5,216,262	06/1/93	Tsu	257	17	03/2/92
	AF	5,357,119	10/18/94	Wang et al.	257	18	02/19/93
	AG	5,684,817	11/04/97	Houdre et al.	372	45	05/1/96
	AH	5,683,934	11/4/03	Candelaria	437	134	05/3/96
	AI	5,994,164	11/30/99	Fonash et al.	438	97	03/18/98
	AJ	6,058,127	05/2/00	Joannopoulos et al.	372	92	12/12/97
	AK	6,274,007	08/14/01	Smirnov et al.	204	192	03/14/00
	AL	6,281,518	08/28/01	Sato	257	13	12/3/98
	AM	6,281,532	08/28/01	Doyle et al.	257	288	06/28/99
	AN	6,344,271	02/05/02	Yadav et al.	428	402	03/23/99
	AO	6,472,685	10/29/02	Takagi	257	77	12/2/98
	AP	6,498,359	12/24/02	Schmidt et al.	257	190	05/18/01
	AQ	2003/ 0034529	02/20/03	Fitzgerald et al.	257	369	10/8/02
	AR	2003/ 0057416	03/27/03	Currie et al.	257	19	09/20/02
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub Class	Translation
	AS	02/103767	12/27/02	WO	H01L	21/20	
	AT	2,347,520	09/06/00	GB	G02B	5/18	
	AU						

<b>EXAMINER:</b>	<b>DATE CONSIDERED:</b>
<p><b>*EXAMINER:</b> Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>	

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	Applicant:	MEARS
	Filing Date:	HEREWITH
	Group:	

<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)</b>		
	AV	Xuan Luo et al.; "Chemical Design of Direct-Gap Light-Emitting Silicon", published July 25, 2002 by The American Physical Society; Vol. 89, Number 7
	AW	R. Tsu; University of North Carolina at Charlotte, "Phenomena in Silicon Nanostructure Devices"; published 09/06/2000 © Springer-Verlag 2000
	AX	P.D. Ye et al., "GaAs MOSFET with Oxide Gate Dielectric Grown by Atomic Layer Deposition"; © 2003 Agere Systems, March 2003
	AY	Novikov et al.; "Silicon-based Optoelectronics" © 1999-2003 by John Wiley & Sons, Inc.; pp/ 1-6
	AZ	
	BA	

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